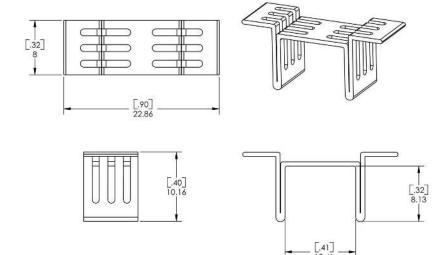
# **Board Level Heat Sinks**



ThermaFlo

## P/N: 834100T00000 & 8341TRT00000





#### PRODUCT SPECIFICATIONS

Devices: D PAK, TO-252
Size: 22.9 x 8.0 x 10.2 mm
Material: Copper, 0.6 mm Thick

Type: Stamped

• PCB Mounting: Surface Mount Technology

· Finish: Tin Plate

Package: Bulk or Tape & Reel

### FEATURES & BENEFITS -

- No Hardware Device Attachment
- Direct SMT Contact to PCB
- Solderable Legs
- RoHS Compliant



#### **CUSTOMIZED HEATSINKS**

- · Specialized Body Configurations
- Contact Applications Engineering

Air Velocity - LFM						
	0	200	400	600	800	1000
ပ္ 50						25 th G
bient -			1			°C/ Watt
Temp Rise Above Ambient (Mounting Surface)			1			
e Abov unting		-			_	Thermal Resistance
np Ris (Mo						Thermal Resistance
		^ F		4.5		0 '
0 0.5 1 1.5 2 2.5 Heat Dissipated - Watts						

Part Number	Packaging	Notes		
834100T00000	Bulk			
8341TRT00000 Tape & Reel		Contact Factory for Tape and Reel Specs		

### **COMAIR ROTRON, INC**